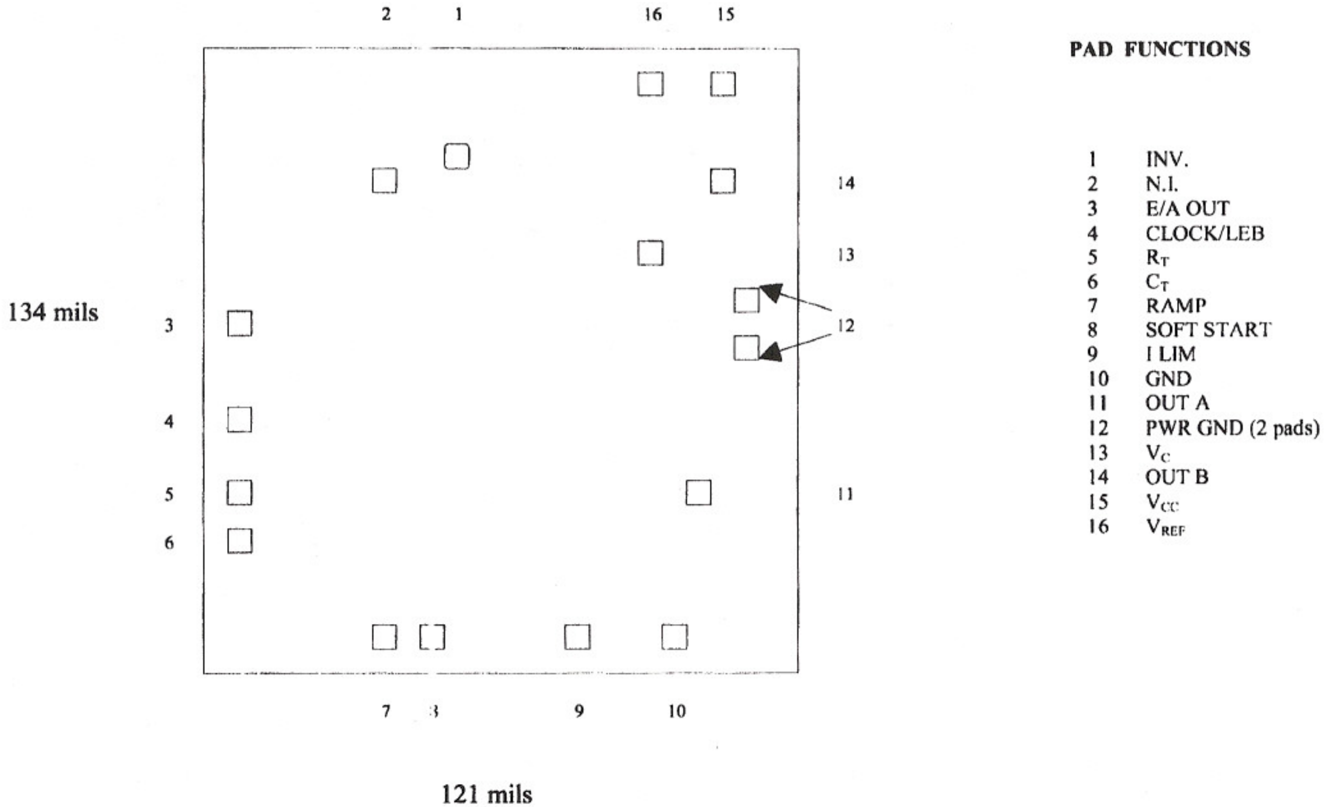
Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423
Phone: 775.783.4940 Fax: 775.783.4947



PAD FUNCTIONS

1	INV.
2	N.I.
3	E/A OUT
4	CLOCK/LEB
5	R_T
6	C_T
7	RAMP
8	SOFT START
9	I LIM
10	GND
11	OUT A
12	PWR GND (2 pads)
13	V_C
14	OUT B
15	V_{CC}
16	V_{REF}

121 mils

NOTE: Both PWR GND pads must be connected

The information given is believed to be correct at the time of issue.
Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

APPROVED		DIE INFORMATION
G.Bibby ………………………….. DATE: 23 Oct 2003	UC2823B UNITRODE	DIMENSIONS (Mils): 121 x 134 x 15 BOND PADS (Mils): 4 x 4 min MASK. REF: JJ GEOMETRY: BACK POTENTIAL: GND
DG 10.1.2 **Rev B, 7/19/02**		METALLISATION TOP: Al BACK: Si